AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (previously presented): A resin composition comprising a resin crystallization promoter comprising vapor grown carbon fibers, each fiber filament of the carbon fibers having a diameter of 0.001 μm to 5 μm and an aspect ratio of 5 to 15,000,

the fibers having undergone a graphitization at 1,500°C or higher, and

the resin composition being obtained by kneading the crystallization promoter with a resin, and subsequently subjecting the resultant mixture to annealing at a temperature of from 55°C higher than the glass transition point of the resin to a temperature 75°C higher than the glass transition point of the resin.

2. (canceled).

3. (currently amended): The resin ~~crystallization promoter~~ composition as claimed in claim 1, wherein the vapor grown carbon fibers contain boron in an amount of 0.001 to 5 mass%.

4. (canceled).

5. (previously presented): The resin composition as claimed in claim 1, wherein the resin is a thermoplastic resin.

6. (original): The resin composition as claimed in claim 5, wherein the thermoplastic resin is an amorphous thermoplastic resin.

7. (original): The resin composition as claimed in claim 5, wherein the thermoplastic resin is a resin containing a polymer including a structural unit having an aromatic group as a repeating unit.

8. (original): The resin composition as claimed in claim 5, wherein the thermoplastic resin is any species selected among polystyrene, polycarbonate, polyarylate, polysulfone, polyetherimide, polyethylene terephthalate, polyphenylene oxide, polyphenylene sulfide, polybutylene terephthalate, polyimide, polyamide-imide and polyether-ether-ketone; or a mixture thereof.

9. (previously presented): The resin composition as claimed in claim 1, which, when subjected to differential scanning calorimetry (DSC), exhibits an endothermic/exothermic peak which is not associated with change in mass at a temperature other than the glass transition point of the resin.

10. (previously presented): The resin composition as claimed in claim 1, which, when subjected to differential scanning calorimetry (DSC), exhibits an endothermic/exothermic peak attributed to melting or crystallization of the composition, wherein the peak is higher or the peak shifts to a higher temperature region, as compared with the case of a resin composition which does not contain the resin crystalline promoter.

11. (currently amended): The resin composition as claimed in claim 1, which, when subjected to X-ray diffractometry, exhibits a peak attributed to the resin, and a peak attributed to orderly arrangement of a resin structure.

12. (previously presented): The resin composition as claimed in claim 1, wherein, in X-ray diffractometry, the half width of the band of the diffraction angle (2θ) corresponding to a peak attributed to orderly arrangement of a resin structure is 5° or less.

13. (previously presented): The resin composition as claimed in claim 1, wherein the content of the resin crystallization promoter is 0.1 to 80 mass%.

14. (canceled).

15. (previously presented): An electrically conductive material comprising the resin composition as claimed in claim 1.

16. (previously presented): A thermally conductive material comprising the resin composition as claimed in claim 1.

17. (previously presented): A material exhibiting tribological characteristics comprising the resin composition as claimed in claim 1.

18. (previously presented): A mechanism part comprising the resin composition as claimed in claim 1.